

RoHS Compliant **HF**

REV.	ECN.NO.	MODIFY.CONTENT
X1	2023-03-14	NEW

NOTES:

1. FINISH:

- 1.1 HOUSING: POLYAMIDE BLACK,UL94V-0.
- 1.2 CONTACT: PHOSPHOR BRONZE. GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVER ALL.
- 1.3 GROUND: BRASS,80u" MIN MATTE TIN PLATED OVER 50u" MIN NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 0.5A/PIN
- 2.2 VOLTAGE RATING: 125V AC/DC.
- 2.3 CONTACT RESISTANCE: 65mΩ MAX.
- 2.4 INSULATION RESISTANCE: 250V DC/0.1S/1000MΩ

3.Max Processing Temp:265°C Seconds 40S

4.FLOATING RANGE OF THIS CONNECTOR IS 0.7MM MAX.

THE MAXIMUM CYCLE TIME OF THE FLOATING OPERATION IS IN ACCORDANCE WITH THE MATING CYCLE OF THE CONNECTOR

5.PLEASE USE THE CONNECTORS WITHIN THE SPECIFIED PCB DISTANCE.

PLEASE REFER TO THE DRAWINGS OF MATING CONNECTOR

6.BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS

7.ORDER INFORMATION:

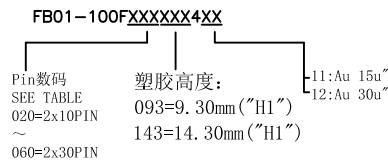
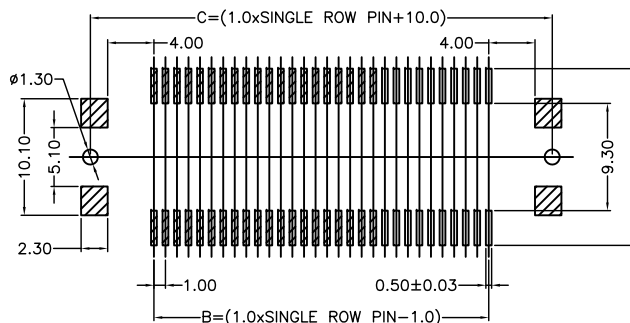
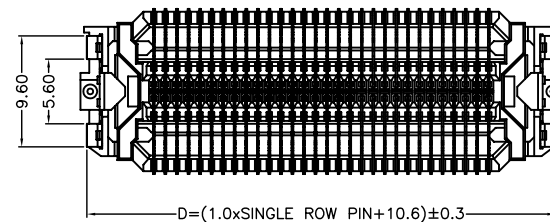
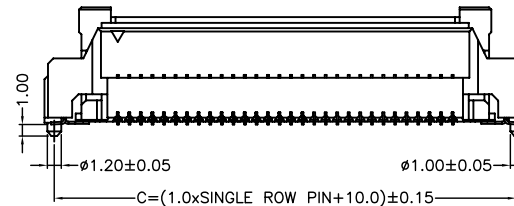
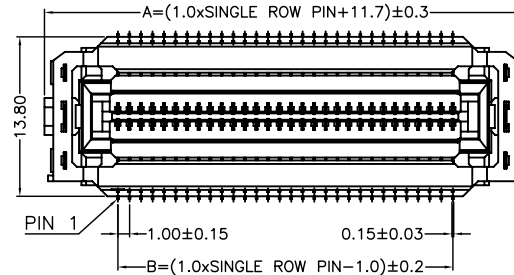
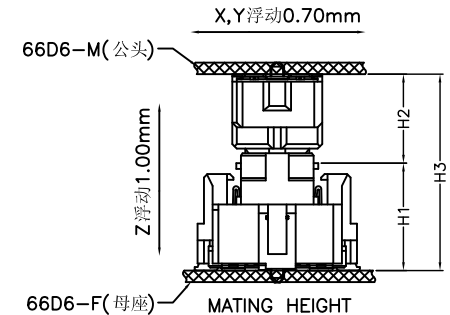
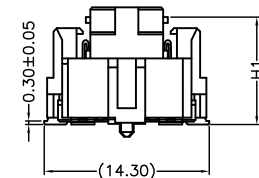
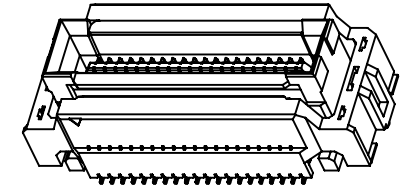


TABLE:

No. OF PIN	A	B	C	D
020=2x10PIN	21.70	9.00	20.00	20.60
030=2x15PIN	26.70	14.00	25.00	25.60
040=2x20PIN	31.70	19.00	30.00	30.60
050=2x25PIN	36.70	24.00	35.00	35.60
060=2x30PIN	41.70	29.00	40.00	40.60



RECOMMENDED PCB LAYOUT
PCB BOARD TOLFRANCF±0.05



H1	H2	"H3" MATING HEIGHT
9.30	4.70	15.00
	7.70	18.00
	9.70	20.00
14.30	4.70	20.00
	7.70	23.00
	9.70	25.00

GENERAL TOLERANCE	DWG.NO.	F B01-100F XXXXXX400	PART.NO.	F B01-100F XXXXXX4XX	DRAWN	Brian 2023-03-14
x.±0.50	REV.	X1	TITLE	浮动板对板1.0Pitch母座	CHECKED	
.x±0.25	SIZE	A4	SHEET	1 OF 1	APPROVED	
.xx±1°						

UNIT mm SCALE 1:1

OLN 东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.